

## 产品应用

- 无线通信(Wi-Fi, BT, BLE, UWB, NFC, Zigbee)
- 有线通信(Ethernet, USB2.0/3.0)
- 微机(CPU, MPU, DSP)

HDD, SSD, 电脑, 医疗保健, 无线模块, 头戴式耳机, OTT(Over The Top), 游戏设备, 照明设备, HEMS/BEMS等

## 产品特性

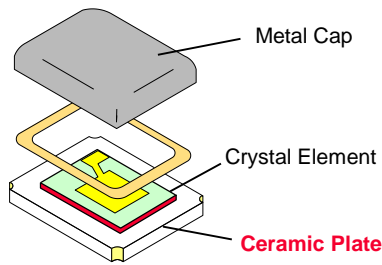
### ■ 小尺寸

16 to 50MHz: 2.0mm x 1.6mm

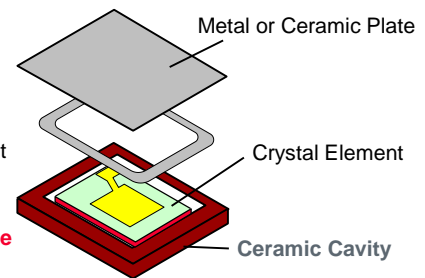
### ■ 经济性与独特设计

使用村田独特的封装技术, 结构简单  
独创的不良产品检测技术, 可靠性强

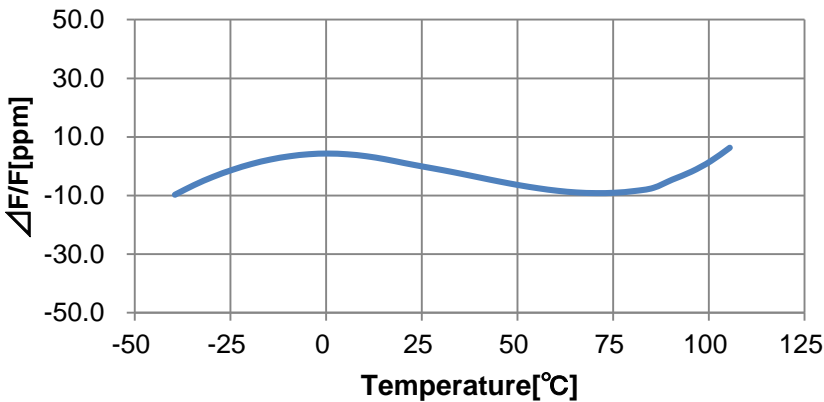
Murata Crystal Unit



Conventional Crystal Unit



## 温度特性



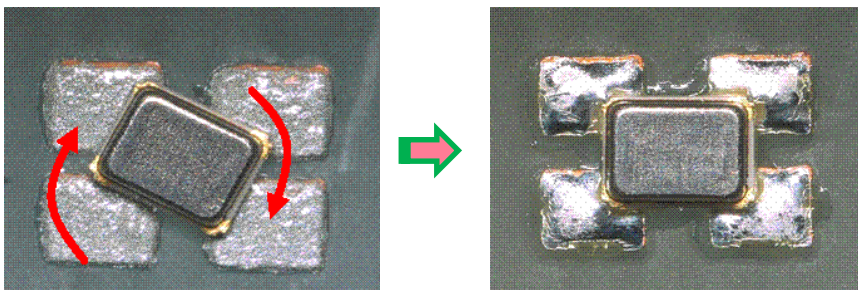
※此温度特性曲线所代表的产品为:  
XRCGB25M000F3M00R0.

## 兼容性

XRCGB系列在贴装到3225晶振焊盘上后可保持正确的焊接位置

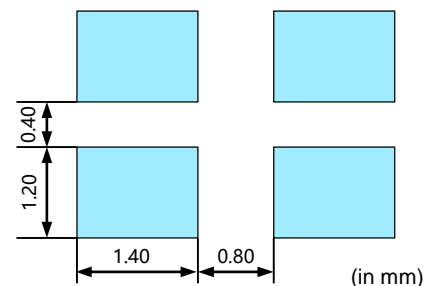
Before reflow

After reflow



实验用3225焊盘图

(Land pattern for 3.2mm x 2.5mm crystal)



产品一览

系列	型号	频率(MHz)	频率公差 (ppm max.)	频率温度特性 (ppm max.)	ESR (ohm max.)	频率老化 (ppm/Y)	负载容量 (pF)			
XRCGB_F_H	XRCGB24M000F1H00R0	24.0000	±10	±10 (-20 ~ +70 °C)	80	±2	6±0.1			
	XRCGB25M000F1H00R0	25.0000								
	XRCGB26M000F1H00R0	26.0000								
	XRCGB32M000F1H00R0	32.0000								
XRCGB_F_S	XRCGB37M400F1S1AR0	37.4000		±10	±10 (-30 ~ +85 °C)			60	±2	6±0.1
	XRCGB38M400F1S1AR0	38.4000								
	XRCGB40M000F1S1AR0	40.0000		±20 (-40 ~ +105 °C)	50					
	XRCGB37M400F1S2FR0	37.4000			60					
	XRCGB38M400F1S2FR0	38.4000			50					
	XRCGB40M000F1S2FR0	40.0000								
XRCGB_F_N	XRCGB16M000FXN00R0	16.0000		±40(Total) (-30 ~ +85 °C)				200		
XRCGB_F_P	XRCGB24M000F2P00R0	24.0000		±20	±20 (-30 ~ +85 °C)			150	±5	6±0.1
	XRCGB25M000F2P00R0	25.0000								
	XRCGB26M000F2P00R0	26.0000								
	XRCGB27M000F2P00R0	27.0000								
	XRCGB27M120F2P00R0	27.1200	±20	±20 (-30 ~ +85 °C)	100					
	XRCGB30M000F2P00R0	30.0000								
	XRCGB31M250F2P00R0	31.2500								
	XRCGB32M000F2P00R0	32.0000								
XRCGB_F_M	XRCGB24M576F3M00R0	24.5760	±30	±40 (-30 ~ +85 °C)	150	±5	6±0.1			
	XRCGB33M868F4M00R0	33.8688								
	XRCGB40M000F4M00R0	40.0000	±45	±40 (-30 ~ +85 °C)	100					
	XRCGB48M000F4M00R0	48.0000			65					
	XRCGB50M000F4M00R0	50.0000								

\*关于产品如有任何要求，请联系村田销售或技术人员。

尺寸规格和推荐焊盘

(in mm)

